



K22BPF2

chip dimensions: 320 x 40 mils
substrate: 5 mil thick Alumina
metalization: WTI with 200u" Au for wire bonding
resistors: TaN, 50 Ohms/square
vias: 3 mil diameter, plated-thru
layers:

chip outline = cyan
top metal = black
backside metal = blue
vias = green
resistors = red

NATIONAL RADIO ASTRONOMY OBSERVATORY

1180 Boxwood Estate Rd, Charlottesville, VA, 22903

NAME: k22bpf2

FILE: k22bpf2.dwg

DATE: 12/13/2007

BY: Matthew A. Morgan

E-MAIL: matt.morgan@nrao.edu